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Silicon NPN Epitaxial

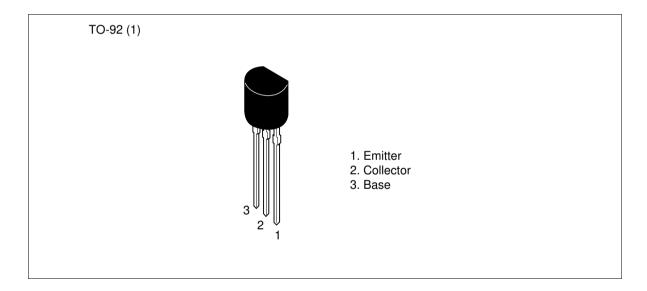


ADE-208-1048 (Z) 1st. Edition Mar. 2001

Application

- Low frequency amplifier
- Complementary pair with 2SA673 and 2SA673A

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	2SC1213	2SC1213A	Unit
Collector to base voltage	V_{CBO}	35	50	V
Collector to emitter voltage	V _{CEO}	35	50	V
Emitter to base voltage	V _{EBO}	4	4	V
Collector current	I _c	500	500	mA
Collector power dissipation	P _c	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

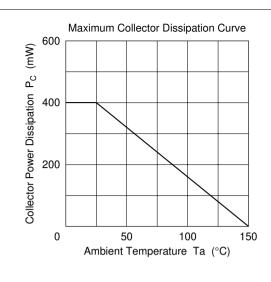
Electrical Characteristics (Ta = 25° C)

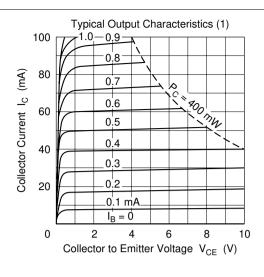
		2SC1	213		2SC1213A				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	35	_	_	50	_	_	V	$I_{\rm C} = 10 \; \mu A, \; I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	35	_	_	50	_	_	V	$I_{\text{C}} = 1 \text{ mA}, R_{\text{BE}} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	4	_	_	4	_	_	V	$I_E = 10 \ \mu\text{A}, \ I_C = 0$
Collector cutoff current	I _{CBO}	_	_	0.5	_	_	0.5	μΑ	V _{CB} = 20 V, I _E = 0
DC current tarnsfer ratio	h _{FE} *1	60	_	320	60	_	320		$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}$
	h _{FE}	10	_	_	10	_	_		$V_{CE} = 3 \text{ V},$ $I_{C} = 500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	0.2	0.6	_	0.2	0.6	V	$I_{\rm C} = 150 \text{ mA},$ $I_{\rm B} = 15 \text{ mA}^{*2}$
Base to emitter voltage	V _{BE}	_	0.64	_	_	0.64	_	V	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}$

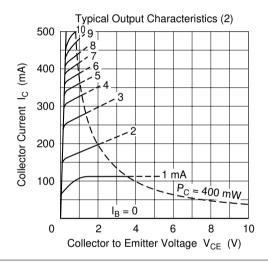
Notes: 1. The 2SC1213 and 2SC1213A are grouped by \mathbf{h}_{FE} as follows.

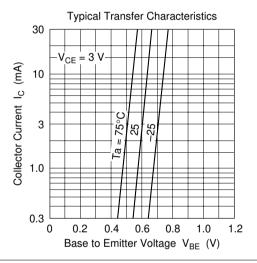
2. Pulse test

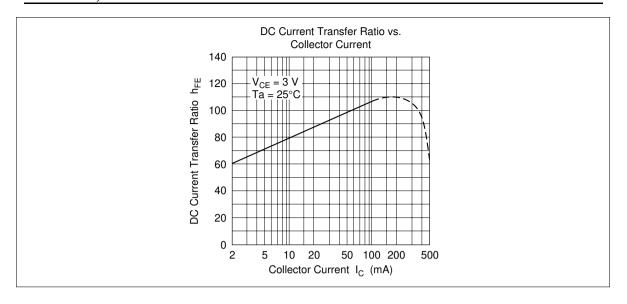
В	С	D		
60 to 120	100 to 200	160 to 320		



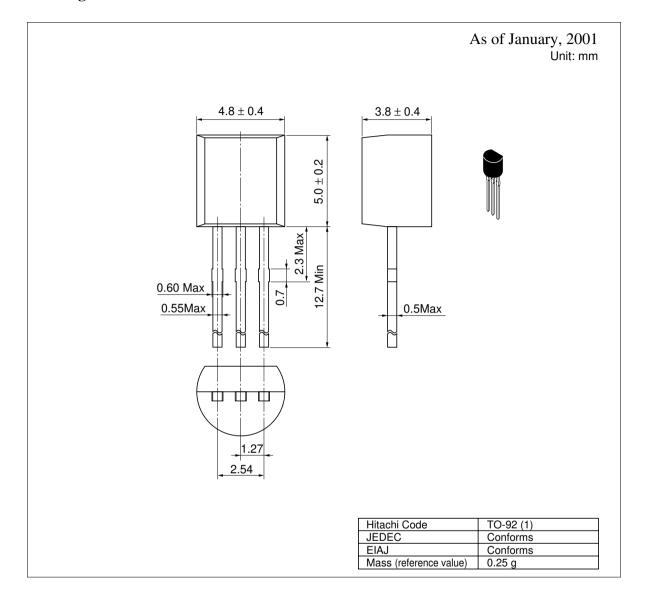








Package Dimensions



5

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